



Smart Structures and Applications

Guest Editor:

Dr. Mohammad Arefi

Department of Solid Mechanics,
Faculty of Mechanical
Engineering, University of
Kashan, Kashan 87317-51167,
Iran

Deadline for manuscript
submissions:

closed (15 September 2023)

Message from the Guest Editor

Dear Colleagues,

The scope of this Special Issue involves the presentation of novel structures and systems composed of piezoelectric and piezomagnetic materials and structures as sensors or actuators in electromechanical and electromagnetic systems based on advanced methods of analysis and investigation. Smart materials may be used in various geometries, configurations, and patterns, such as rods, beams, plates, shells, and sandwich structures. The significant effects of multi-field loads on the smart and intelligent structures have the potential to serve as important contributions in the wider context of mechanical engineering. This Special Issue invites submissions of papers discussing the size-dependent analysis of intelligent systems and structures in micro- and nanoscales using innovative and relevant theories.

The Special Issue also welcomes research that addresses the various applications of intelligent material and structures, as well as the experimental works in relation to the control of systems and energy-harvesting applications.





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Editor-in-Chief

Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Message from the Editor-in-Chief

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Micromachines Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

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